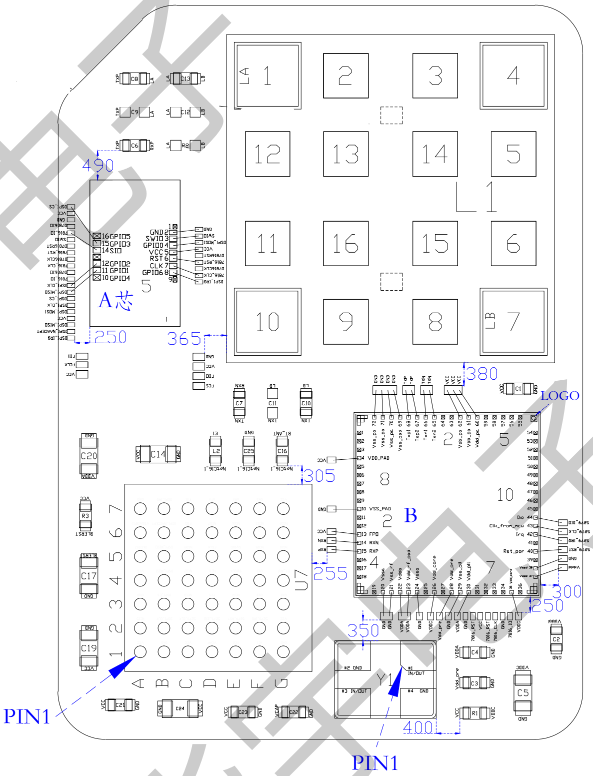
池州华宇电子科技股份有限公司
CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD

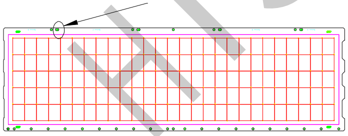
焊线图纸 Bonding Diagram

客户代码 Customer No.		线图号 Drawing No.			页码 Page 1 /5
产品名称 Product Type			封装外型 PKG Type	LGA6L(12.3×8.8×0.77-P2.54)	

焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
金丝 Au	20			751	401	首选(Preferred)：G760L TypeA 备选(Optional)：	
客户图号 Customer drawing NO.							



框架传送方向（装片）：
L/F Direction（D/A）：椭圆孔朝上



实物图：
Chip photo：

特殊说明 Special Instructions：

DB注意：
1.装片位置公差为±30um;
2.控制溢胶，为WB预留焊线位置。

WB注意：
数字为不打线pad点个数。

说明 Instructions	粘片胶类型 epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPO (μm²)	最小焊盘间距 Min BPP(μm)	铝垫厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Street line (μm)	晶圆尺寸 Wafer Size	是否是 Low-K If low-k ?	减薄厚度 (μm) Wafer Thickness
A芯： DIE A	绝缘胶 (Non-conductive) 2025DSI		2456.873*1514.744μm²) 96.73*59.64(mil²)	73*104	104	1.2	是/YES	62	12	是/YES 40nm	150±10 来料厚度
B芯： DIE B	绝缘胶 (Non-conductive) 2025DSI		3070*3040μm²) 120.86*119.69(mil²)	60*60	142	1	否/N0	60	8	否/N0	150 来料厚度
C芯： DIE C											
D芯： DIE D											
E芯： DIE E											
F芯： DIE F											
G芯： DIE G											

拟制 Prepared by		制图日期 Create Date	2024/6/3	生效日期 Effective Date		客户确认签字/盖章： Customer Signature
研发审核 R&d check		产品工程审核 Product engineering check		批准 Approved by		

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焊线图纸 Bonding Diagram

客户代码 Customer No.		线图号 Drawing No.		页码 Page 2 / 5
产品名称 Product Type		封装外型 PKG Type	LGA6L(12.3×8.8×0.77-P2.54)	

焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
金丝 Au	20			751	401	首选(Preferred)：G760L-TypeA 备选(Optional)：	
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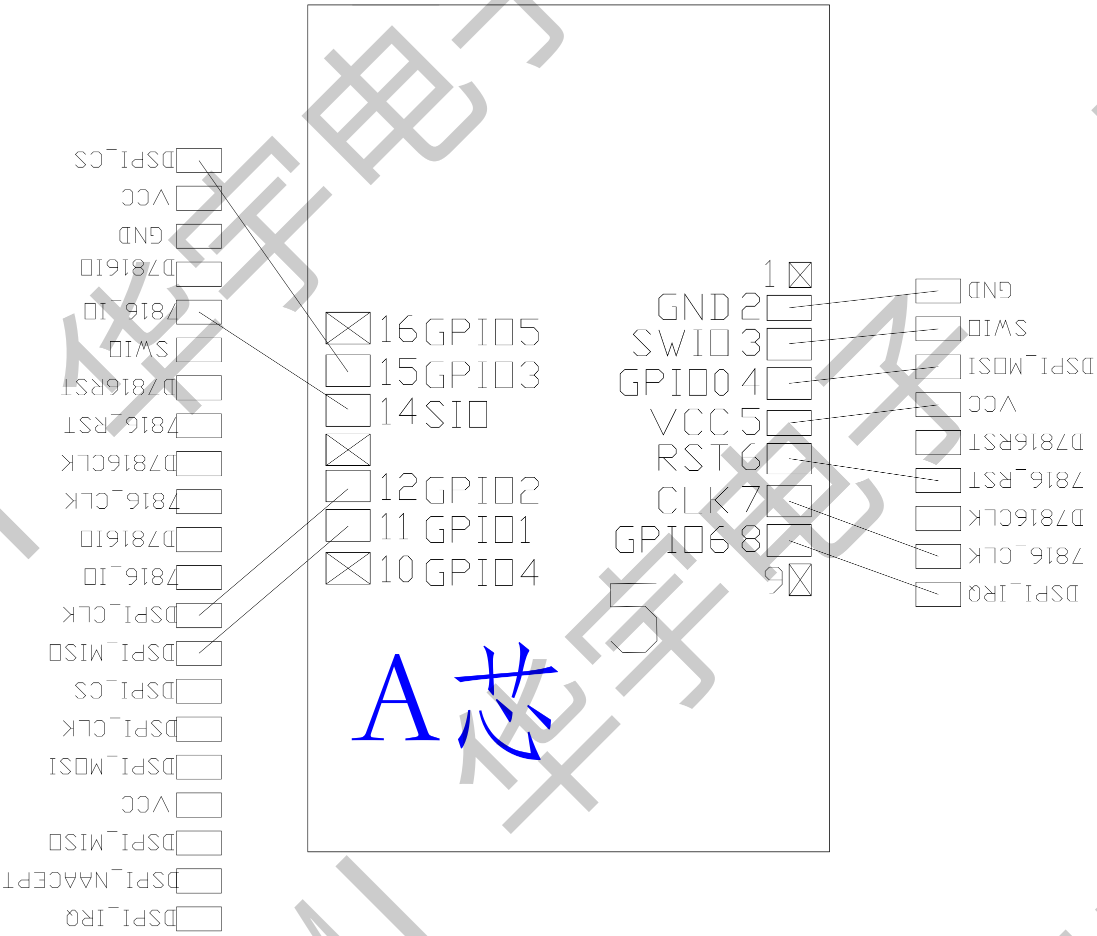

实物图： Chip photo：	特殊说明 Special Instructions： DB注意： 装片位置公差为±30um； WB注意： 数字为不打线pad点个数。

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焊线图纸 Bonding Diagram	产品名称 Product Type		封装外型 PKG Type	LGA6L(12.3×8.8×0.77-P2.54)	

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金丝 Au	20			751	401	首选(Preferred)：G770-HCD备选 (Optional)：	

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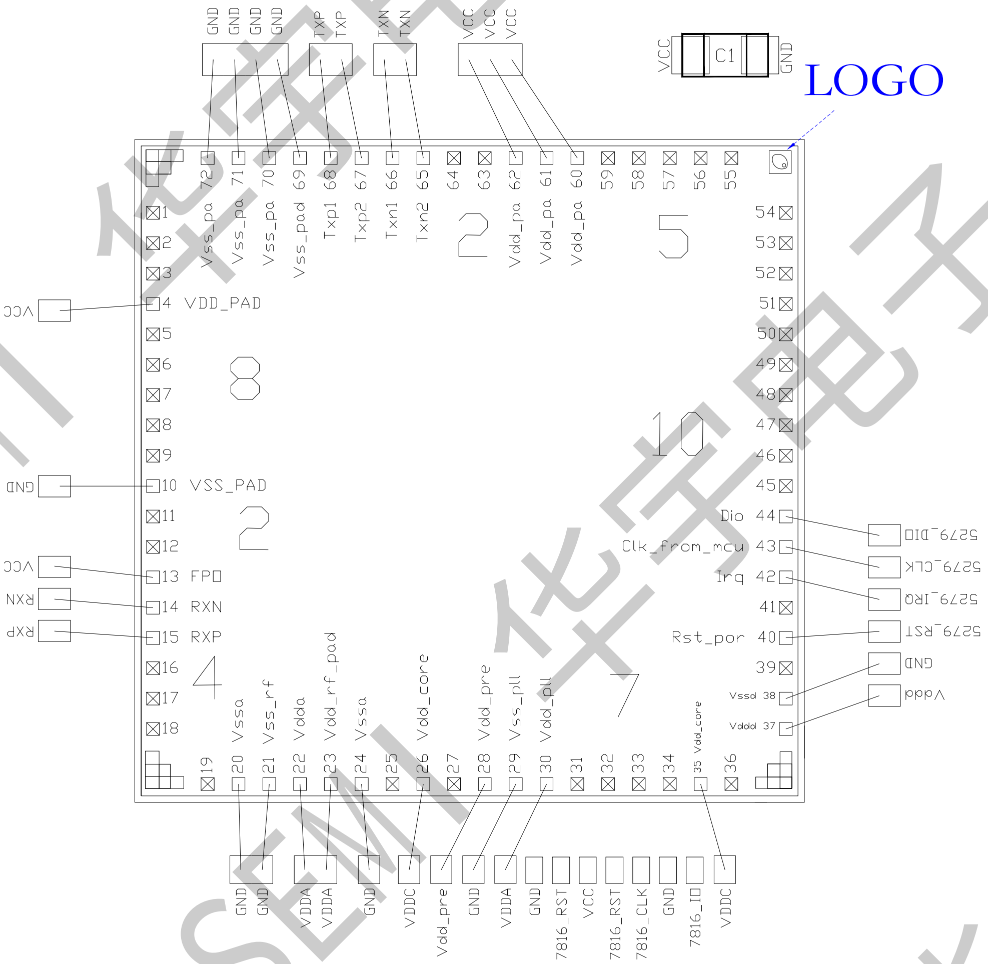

实物图：
Chip photo:

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焊线图纸 Bonding Diagram

客户代码 Customer No.		线图号 Drawing No.				页码 Page 4 / 5	
产品名称 Product Type			封装外型 PKG Type	LGA6L(12.3×8.8×0.77-P2.54)			
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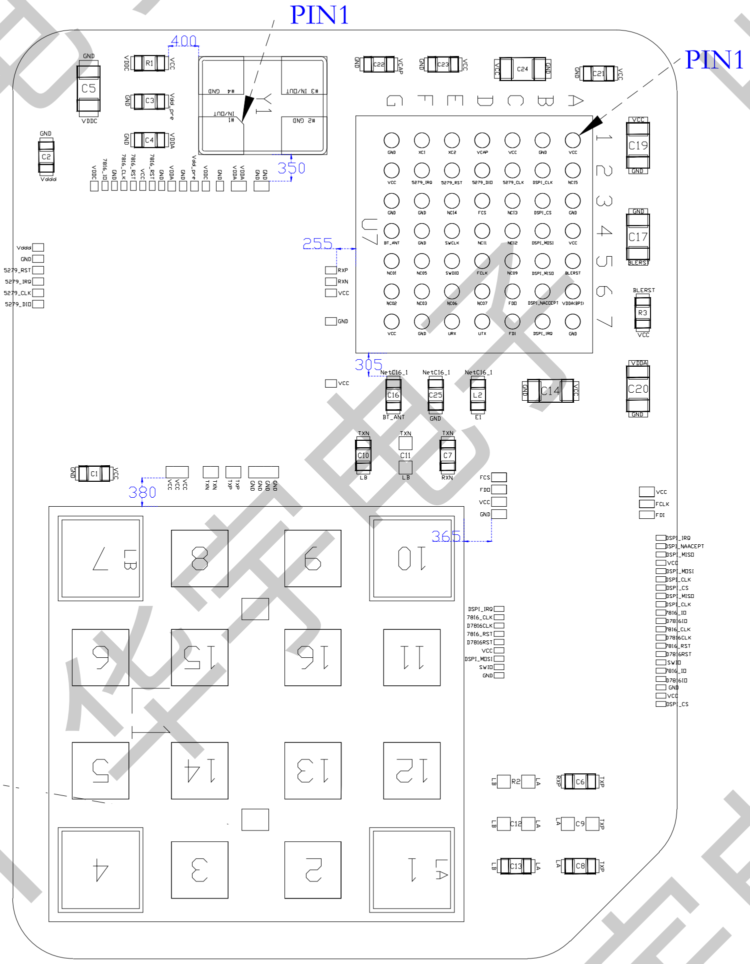
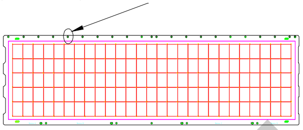
客户图号 Customer drawing NO.							



框架传送方向（装片）：
L/F Direction（D/A）：圆孔朝上



NO.	Item	Reference	value	package	KD P/N	Quantity
1	IC	U7	ST BlueNRG355			1
2	片式电容	C1,C2,C3,C4	0.47uF 6.3V X5R 20%	01005		4
3	片式电容	C6,C7	56pF 16V C0G 2%	01005		2
4	片式电容	C8,C10	180pF 16V C0G 2%	01005		2
5	片式电容	C13	68pF 16V C0G 2%	01005		1
6	片式电容	C14,C19,C24	2.2uF 10V X5R 20%	0201		3
7	片式电容	C5,C17	1uF 10V X5R 20%	0201		2
8	片式电容	C16	220pF 16V C0G 5%	01005		1
9	片式电容	C20	0.1uF 16V X5R 20%	0201		1
10	片式电容	C21,C23	0.1uF 10V X5R 20%	01005		2
11	片式电容	C22	220nF 6.3V X5R 20%	01005		1
12	片式电容	C25	1.5pF 16V C0G +/-0.25pF	01005		1
13	电感	L1	NFC天线	5555		1
14	电感	L2	2.4nH 450mA +/-0.1nH	01005		1
15	片式电阻	R1	22R 1/32W 1%	01005		1
16	片式电阻	R3	100K 1/32W 1%	01005		1
17	晶振	Y1	XTAL 1.6x1.2mm			1
18	基板	substrate	基板	/		1
19	锡膏	/	F590 SnCu0.7-89M4	/		/
		SMT元器件总计				27

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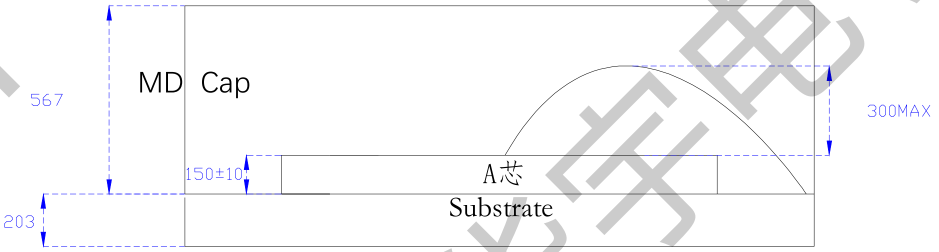

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